

REMARKS

Claims 78-108 of the present continuation application are directed to a method for fabricating a semiconductor component, such as a semiconductor package 130 (Figure 8). The method includes the step of providing a substrate 10 (Figure 1A) having a first side (face side 14-Figure 1A) and a second side (backside 16-Figure 1A). The method also includes the step of forming a plurality of openings 30 (Figure 1B) in the substrate 10, extending from the first side (face side 14-Figure 1A) to the second side (backside 16-Figure 1A). In addition, the method includes the step of forming conductive members 34 (Figure 1D) in the openings 30 by depositing a solder metal into the openings 30 using capillary action or a solder wave (page 12, lines 22-25 of the specification).

Also being submitted with this continuation application is an Information Disclosure Statement. Favorable consideration and allowance of claims 78-108 is respectfully requested. Should any issues arise that will advance this case to allowance, the Examiner is asked to contact the undersigned by telephone.

DATED this 31st day of March, 2004.

Respectfully submitted:



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